

isc N-Channel MOSFET Transistor

IRLR3636, IIRLR3636

• FEATURES

- Static drain-source on-resistance:
 $R_{DS(on)} \leq 6.8m\Omega$
- Enhancement mode:
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• DESCRIPTION

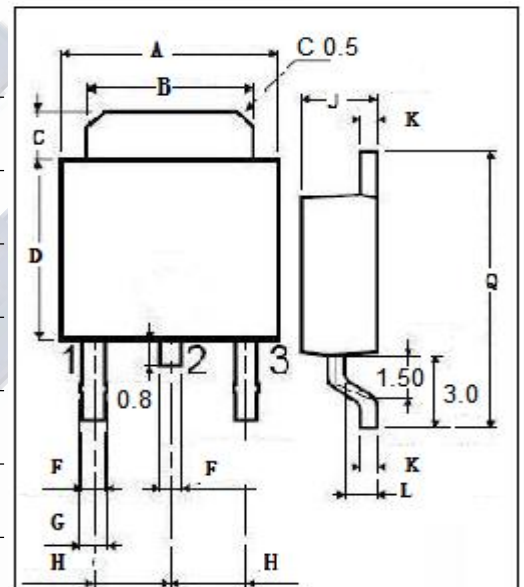
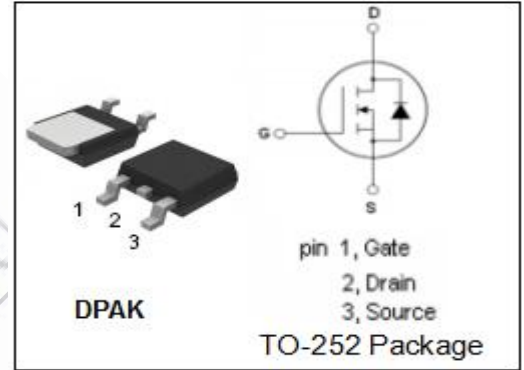
- High Speed Power Switching

• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ C$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 16	V
I_D	Drain Current-Continuous	99	A
I_{DM}	Drain Current-Single Pulsed	396	A
P_D	Total Dissipation @ $T_c=25^\circ C$	143	W
T_j	Max. Operating Junction Temperature	175	$^\circ C$
T_{stg}	Storage Temperature	-55~175	$^\circ C$

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(j-c)}$	Channel-to-case thermal resistance	1.05	$^\circ C/W$
$R_{th(j-a)}$	Channel-to-ambient thermal resistance	110	$^\circ C/W$



DIM	mm	
	MIN	MAX
A	6.40	6.60
B	5.20	5.40
C	1.15	1.35
D	5.70	6.10
F	0.65	
G	0.75	
H	2.10	2.50
J	2.10	2.40
K	0.40	0.60
L	0.90	1.10
Q	9.90	10.1

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ELECTRICAL CHARACTERISTICS

 T_C=25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V; I _D =250 μ A	60			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ; I _D =100 μ A	1		2.5	V
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =10V; I _D =50A			6.8	mΩ
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±16V			±0.1	μ A
I _{DSS}	Drain-Source Leakage Current	V _{DS} =60V; V _{GS} = 0V			20	μ A
V _{SD}	Diode forward voltage	I _s =50A, V _{GS} = 0V			1.3	V